

## DESCRIPTION

The MB1S~MB10S are available in MBS package.

# FEATURES

- Glass Passivated Chip Junction
- Reverse Voltage 100 to 1000V
- Forward Current 0.8A
- High Surge Current Capability
- Designed for Surface Mount Application
- Available in MBS package

#### MECHANICAL DATA

Case: MBS

Terminals: Solderable per MIL-STD-750,

Method 2026

Approx. Weight: 100mg /0.0035oz

Package Type	Part Number					
MBS	MB1S					
	MB2S					
	MB4S					
	MB6S					
	MB8S					
	MB10S					
Note	SPQ: 3,000pcs/Reel					
AiT provides all RoHS Compliant Products						

**ORDERING INFORMATION** 

#### REV1.0 - AUG 2017 RELEASED -



### MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified. Single phase half wave 60Hz, resistive or inductive load, for capacitive load current derate by 20 %.

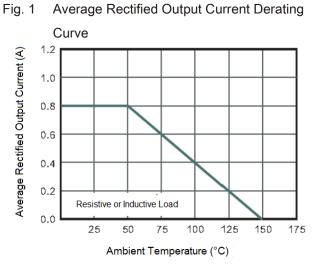
Paramet	er	Symbols	MB1S	MB2S	MB4S	MB6S	MB8S	MB10S	Unit	
Maximum Repetitive		100	200	400	600	800	1000	V		
Reverse Voltage	V <sub>RRM</sub>	100	200	400	000	800	1000	v		
Maximum RMS Volta	Vrms	70	140	280	420	560	700	V		
Maximum DC Blockir	V <sub>DC</sub>	100	200	400	600	800	1000	V		
Average Rectified Ou	la	lo 0.8								
at T <sub>A</sub> = 50°C	10									
Peak Forward Surge Current,			30							
8.3ms Single Half Sir	Ifsm									
Superimposed on Rated Load		30								
(JEDEC method)										
Maximum Forward	at 0.4 A	VF	1.0							
Voltage	at 0.8 A	v i	1.1							
Maximum DC			5							
Reverse Current	@T <sub>A</sub> =25°C	IR								
at Rated DC	Rated DC @T <sub>A</sub> =125°C		40							
Blocking Voltage										
Typical Junction Cap	CJ	13						pF		
Typical Thermal ResistanceNOTE2		Reja	95							
		R <sub>θJL</sub>	30							
Operating and Storage		Tj, Tstg	-55 ~ +150							
Temperature Range	13, 1516			-00	. 100			°C		

NOTE1: Measured at 1MHz and applied reverse voltage of 4 V D.C.

NOTE2: Mounted on glass epoxy PC board with  $4 \times (5 \times 5 \text{mm}^2)$  copper pad.



#### TYPICAL PERFORMANCE CHARACTERISTICS





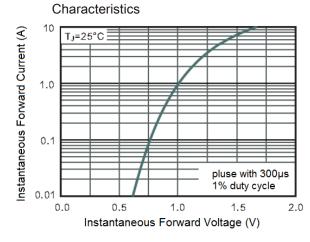


Fig. 5 Maximum Non-Repetitive Peak Forward Surge Current

Fig. 2 Typical Reverse Characteristics

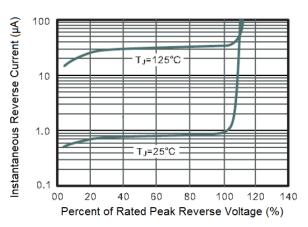
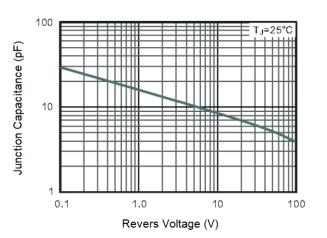
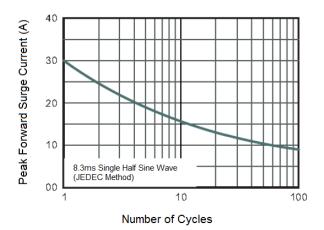


Fig. 4 Typical Junction Capacitance



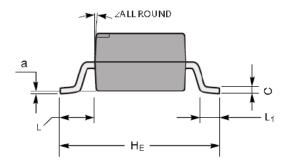


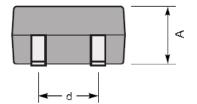


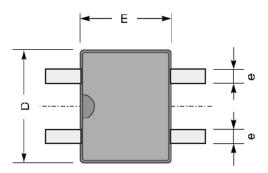


# PACKAGE INFORMATION

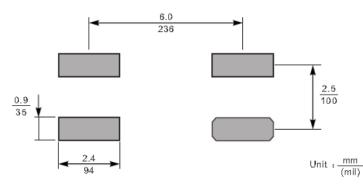
Dimension in MBS Package (Unit: mm) Plastic surface mounted package; 4 leads







#### The recommended mounting pad size



UNIT		А	С	D	E	HE	d	е	L	L <sub>1</sub>	а	2
mm	max	2.6	0.22	5.0	4.1	7.0	2.7	0.7	1.7	1.1	0.2	70
	min	2.2	0.15	4.5	3.6	6.4	2.3	0.5	1.3	0.5	-	
mil	max	102	8.7	197	161	276	106	28	67	43	8	1
	min	94	5.9	177	142	252	91	20	51	20	-	



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